



DESCRIPTION

Lingsen' SMA (light sensor) is a substrate based, clear and LCP cap encapsulated package. It is available in pin count is 8 or can be customized to individual customer needs.

It is widely used for each kinds of optical sensor which combine LED and sensor

APPLICATIONS

- Gesture.
- Proximity Sensor.
- Pulse + SpO₂ Sensor.
- Ambient Sensor.

FEATURES

- Meet industrial particle/foreign material level requirements.
- Pin count range is 6/8.
- Lead pitch of 1.01/1.075 mm.

SPECIFICATIONS

Substrate: BT-832NX.
 Die Attach: Silver epoxy
 Gold Wire: 99.99%Au.
 Molding Compound: NT-330HQ-10000.
 LCP cap: MG-350
 Packing: Antistatic plastic.

PACKAGE AVAILABILITY

Package Size (mm)	Lead Pitch (mm)	Lead Count
3.0x2.36	0.97	6
3.94x2.36	0.97	8
4x2	1.075	8

RELIABILITY

Pre-con: MSL3	260°C IR Reflow x 1
Temperature Cycling	-40°C/85°C, 1000 cycles.
High Temperature Storage	85°C, 1000 hrs
Temperature & Humidity Test	85°C, 85%R.H., 1000hrs

THERMAL PERFORMANCE

Package	Body size (mm)	Pad size (mm)	Die size (mm)
6	3X2.36	0.72x0.72	1.25x0.84/0.25x0.25
8	3.94X2.36	0.72x0.72	1.33x0.92/0.25x0.25
8	4X2	0.43x0.675	1.32x1.1/0.25x0.25

ELECTRICAL PERFORMANCE

Package	Body size (mm)	Pad size (mm)
6L	3X2.36	0.72x0.72
8L	3.94X2.36	0.72x0.72
8L	4X2	0.43x0.6756

CROSS-SECTION

